

DIGITRON SEMICONDUCTORS

MCR8SD, MCR8SM, MCR8SN

SILICON CONTROLLED RECTIFIERS

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak repetitive off-state voltage⁽¹⁾ Peak repetitive reverse voltage (T _J = -40 to +110°C, sine wave, 50 to 60Hz, gate open) MCR8SD MCR8SM MCR8SN	V _{DRM} V _{RRM}	400 600 800	V
On-state RMS current (180° conduction angles, T _C = 80°C)	I _{T(RMS)}	8	A
Peak non-repetitive surge current (one half-cycle, sine wave, 60Hz, T _J = 110°C)	I _{TSM}	80	A
Circuit fusing (t = 8.3ms)	I ² t	26.5	A ² s
Forward peak gate power (pulse width ≤ 1.0μs, T _C = 80°C)	P _{GM}	5	W
Forward average gate power (t = 8.3ms, T _C = 80°C)	P _{G(AV)}	0.5	W
Forward peak gate current (pulse width ≤ 1.0μs, T _C = 80°C)	I _{GM}	2	A
Operating temperature range	T _J	-40 to +110	°C
Storage temperature range	T _{stg}	-40 to +150	°C

Note 1: V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Maximum	Unit
Thermal resistance, junction to case	R _{θJC}	2.2	°C/W
Thermal resistance, junction to ambient	R _{θJA}	62.5	°C/W
Maximum lead temperature for soldering purposes 1/8" from case for 10s	T _L	260	°C

ELECTRICAL CHARACTERISTICS (T_J = 25°C, unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Peak forward blocking current or reverse blocking current⁽²⁾ (V _D = Rated V _{DRM} or V _{RRM} , R _{GK} = 1kΩ) T _J = 25°C T _J = 110°C	I _{DRM} , I _{RRM}	- -	- -	10 500	μA
ON CHARACTERISTICS					
Peak on-state voltage⁽³⁾ (I _{TM} = 16A)	V _{TM}	-	-	1.8	V
Gate trigger current (continuous dc) ⁽⁴⁾ (V _D = 12V, R _L = 100Ω)	I _{GT}	5.0	25	200	μA
Holding current ⁽⁴⁾ (V _D = 12V, gate open, initiating current = 200mA)	I _H	-	0.5	6.0	mA
Latch current ⁽⁴⁾ (V _D = 12V, I _G = 200μA)	I _L	-	0.6	8.0	mA
Gate trigger voltage (continuous dc) ⁽⁴⁾ (V _D = 12V, R _L = 100Ω) T _J = 25°C T _J = -40°C	V _{GT}	0.3 -	0.65 -	1.0 1.5	V

* Pulse width ≤ 2.0ms, duty cycle ≤ 2%.

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DYNAMIC CHARACTERISTICS					
Critical rate of rise of off-state voltage ($V_D = 67\% V_{DRM}$, $R_{GK} = 1K\Omega$, $C_{GK} = 0.1\mu F$, $T_J = 110^\circ C$)	dv/dt	5.0	15	-	V/ μs
Critical rate of rise of on-state current ($I_{PK} = 50A$, $PW = 40\mu sec$, $di_G/dt = 1 A/\mu sec$, $I_{gt} = 10mA$)	di/dt	-	-	100	A/ μs

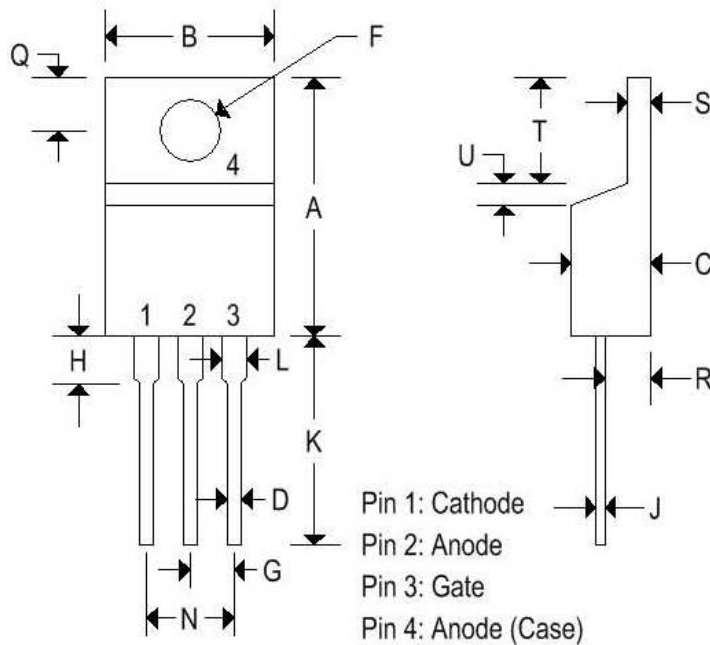
Note 2: $R_{GK} = 1000$ ohms included in measurement.

Note 3: Indicates pulse test: pulse width $\leq 2.0ms$, duty cycle $\leq 2\%$.

Note 4: Does not include R_{GK} in measurement.

MECHANICAL CHARACTERISTICS

Case	TO-220AB
Marking	Alpha-numeric
Pin out	See below



	TO-220AB			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.575	0.620	14.600	15.750
B	0.380	0.405	9.650	10.290
C	0.160	0.190	4.060	4.820
D	0.025	0.035	0.640	0.890
F	0.142	0.147	3.610	3.730
G	0.095	0.105	2.410	2.670
H	0.110	0.155	2.790	3.930
J	0.014	0.022	0.360	0.560
K	0.500	0.562	12.700	14.270
L	0.045	0.055	1.140	1.390
N	0.190	0.210	4.830	5.330
Q	0.100	0.120	2.540	3.040
R	0.080	0.110	2.040	2.790
S	0.045	0.055	1.140	1.390
T	0.235	0.255	5.970	6.480
U	-	0.050	-	1.270
V	0.045	-	1.140	-
Z	-	0.080	-	2.030

Available Non-RoHS (standard) or RoHS compliant (add PBF suffix).

Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.

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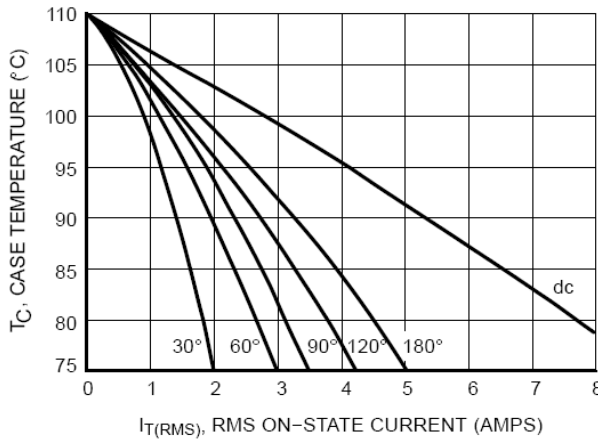


Figure 1. Typical RMS Current Derating

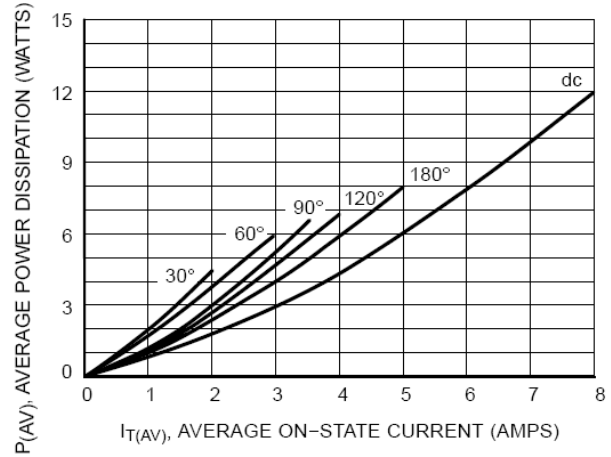


Figure 2. On-State Power Dissipation

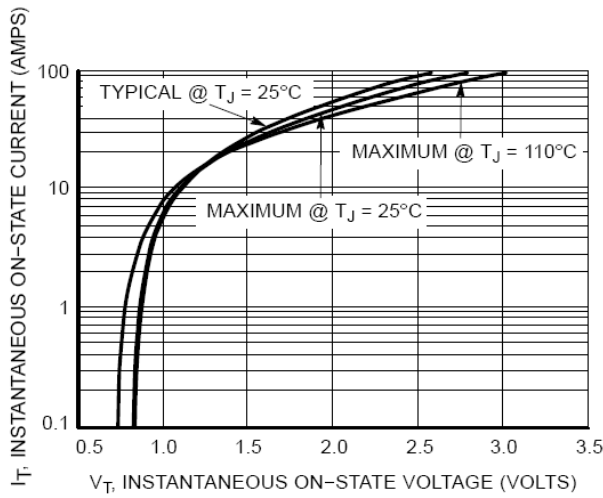


Figure 3. Typical On-State Characteristics

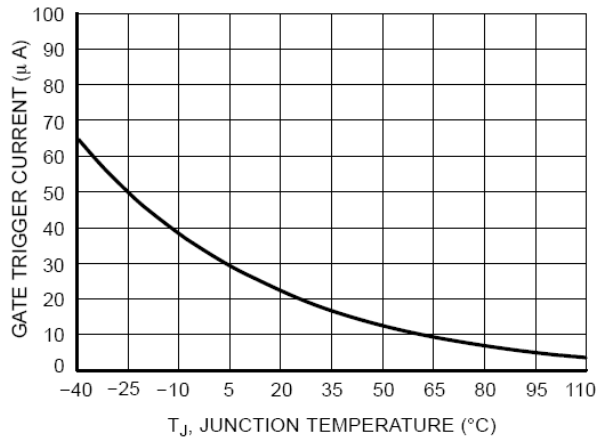


Figure 4. Typical Gate Trigger Current versus Junction Temperature

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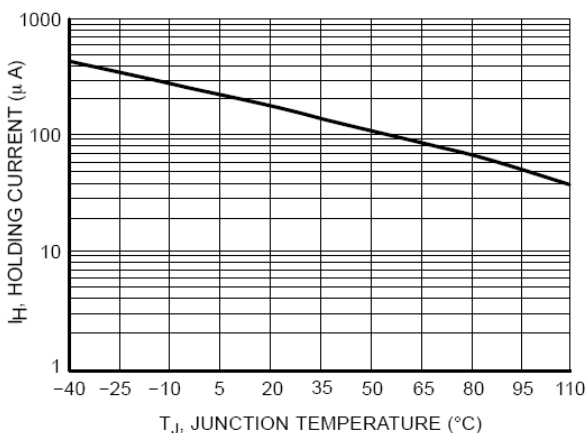


Figure 5. Typical Holding Current versus Junction Temperature

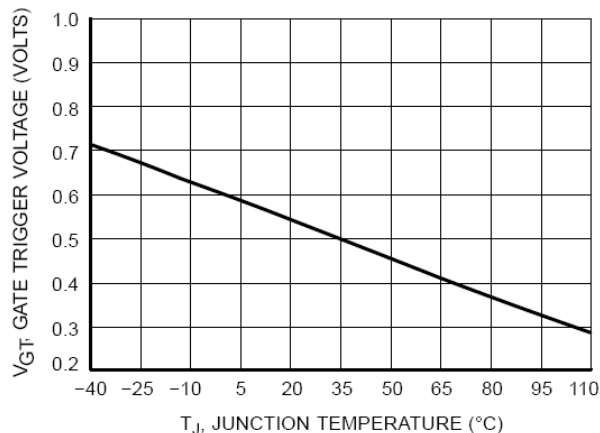


Figure 6. Typical Gate Trigger Voltage versus Junction Temperature

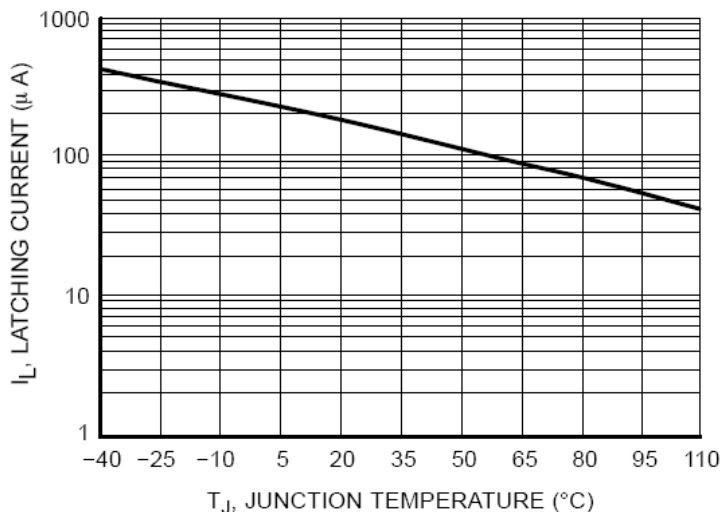


Figure 7. Typical Latching Current versus Junction Temperature